LNJ816C8SRA

Surface Mounting Chip LED

3216 Micro-Lens Type

■ Lighting Color

- Soft Orange

■ Absolute Maximum Ratings T_a = 25°C

Parameter	Symbol	Rating	Unit
Power dissipation	P_D	60	mW
Forward current	I_F	20	mA
Pulse forward current *	I_{FP}	100	mA
Reverse voltage	V_R	3	V
Operating ambient temperature	T_{opr}	–30 to +85	°C
Storage temperature	T_{stg}	–40 to +100	°C

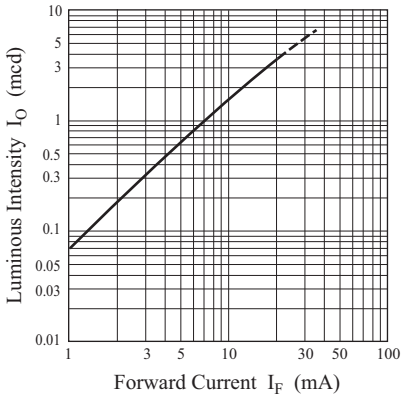
Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

■ Electro-Optical Characteristics T_a = 25°C±3°C

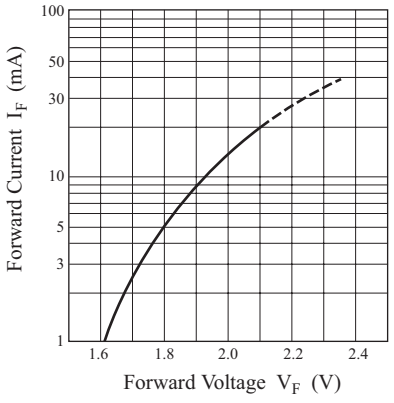
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity *	I_O	I_F = 10 mA	0.80	1.50		mcd
Reverse current	I_R	V_R = 3 V			10	μA
Forward voltage	V_F	I_F = 10 mA		1.93	2.60	V
Peak emission wavelength	λ_P	I_F = 10 mA		610		nm
Spectral half band width	$\Delta\lambda$	I_F = 10 mA		40		nm

Note) *: Measurement tolerance: ±20%

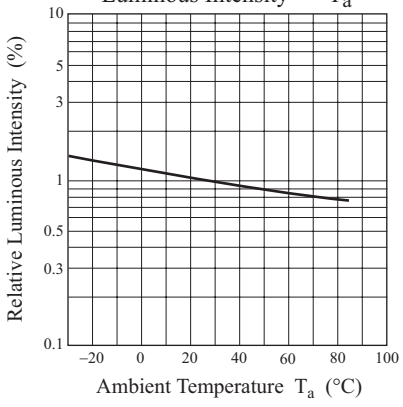
I_O — I_F



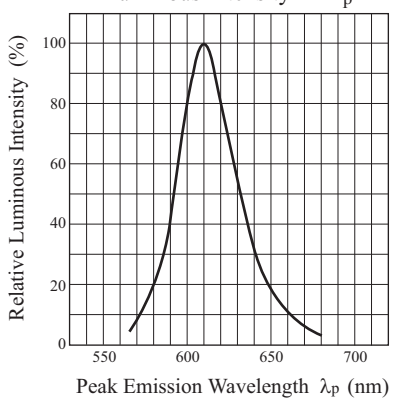
I_F — V_F



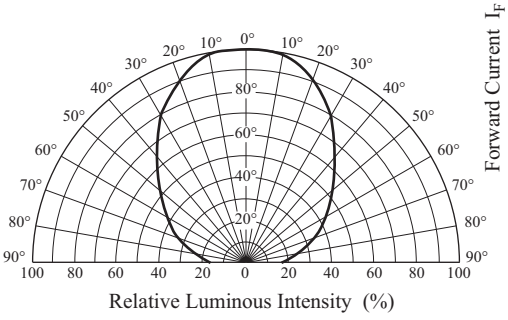
Relative Luminous Intensity — T_a



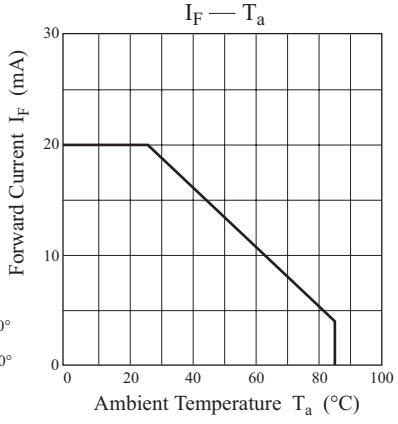
Relative Luminous Intensity — λ_p



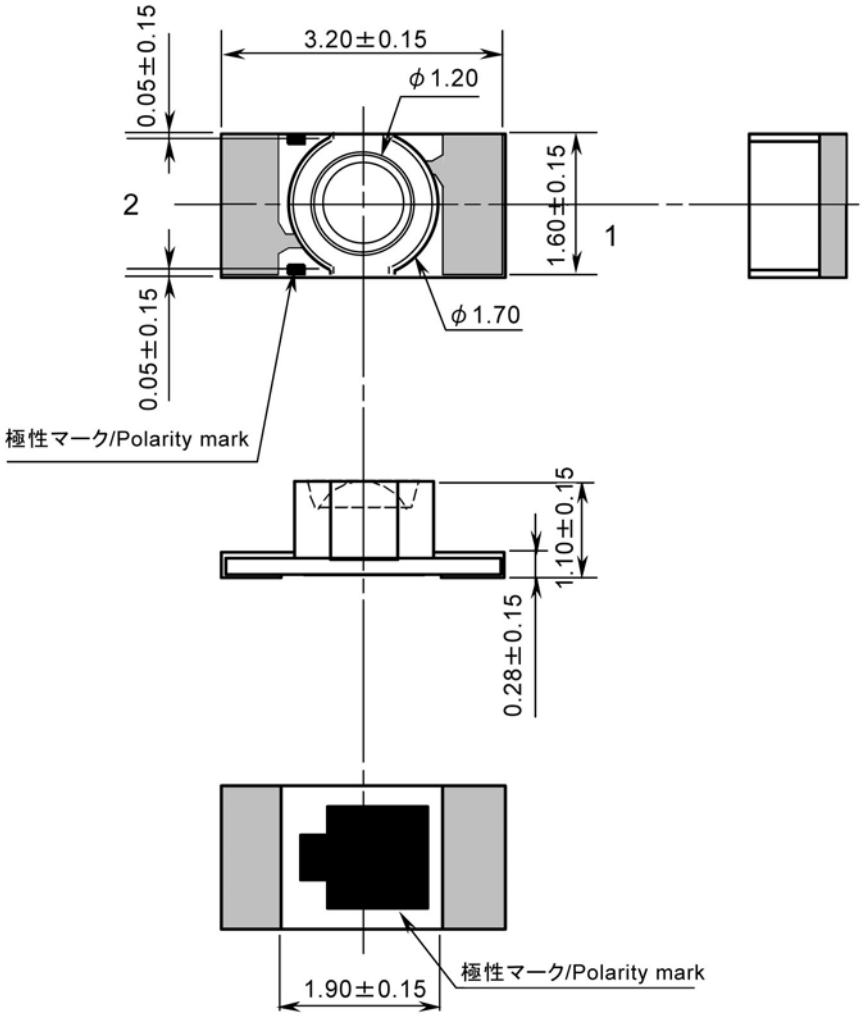
Directive Characteristics



I_F — T_a



■ Package (Unit: mm)



- Pin name
  1: Anode
  2: Cathode

This product complies with the RoHS Directive (EU 2002/95/EC).

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(6) Comply with the instructions for use in order to prevent breakdown and characteristics change due to external factors (ESD, EOS, thermal stress and mechanical stress) at the time of handling, mounting or at customer's process. When using products for which damp-proof packing is required, satisfy the conditions, such as shelf life and the elapsed time since first opening the packages.